



## Material Content Data Sheet



<b>Sales Product Name</b>	IPD50R380CE			<b>Issued</b>	19. July 2018			
<b>MA#</b>	MA001412508							
<b>Package</b>	PG-TO252-3-344			<b>Weight*</b>	323.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.808	1.18	1.18	11760	11760
leadframe	non noble metal	iron	7439-89-6	0.144	0.04		445	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		133	
	non noble metal	copper	7440-50-8	143.904	44.44	44.49	444375	444953
wire	non noble metal	aluminium	7429-90-5	4.431	1.37	1.37	13684	13684
encapsulation	organic material	carbon black	1333-86-4	0.657	0.20		2027	
	plastics	epoxy resin	-	17.726	5.47		54738	
	inorganic material	silicondioxide	60676-86-0	112.921	34.87	40.54	348698	405463
leadfinish	non noble metal	tin	7440-31-5	3.881	1.20	1.20	11986	11986
solder	noble metal	silver	7440-22-4	0.082	0.03		253	
	non noble metal	tin	7440-31-5	0.066	0.02		203	
	non noble metal	lead	7439-92-1	3.134	0.97	1.02	9678	10134
heatspreader	non noble metal	iron	7439-89-6	0.033	0.01		102	
	inorganic material	phosphorus	7723-14-0	0.010	0.00		31	
	non noble metal	copper	7440-50-8	32.995	10.19	10.20	101887	102020
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com